



## Features

- Available in E6 series
- Unit height of 1.8 mm
- Current up to 2.8 A
- Lead free
- RoHS compliant\*

## Applications

- Input/output of DC/DC converters
- Power supplies for:
  - Portable communication equipment
  - Camcorders
  - LCD TVs
  - Car radios

# SRU5018 Series - Shielded SMD Power Inductors

## Electrical Specifications

Bourns Part No.	Inductance 100 KHz		Q Ref.	Test Frequency (MHz)	SRF Min. (MHz)	RDC (mΩ)	I rms Max. (A)	I sat Typ. (A)
	(μH)	Tol. %						
SRU5018-1R0Y	1.0	± 30	9	7.96	200	12.5	2.80	2.85
SRU5018-1R5Y	1.5	± 30	9	7.96	160	15.5	2.50	2.40
SRU5018-2R2Y	2.2	± 30	10	7.96	130	20.5	2.30	2.10
SRU5018-3R5Y	3.5	± 30	9	7.96	90	32.0	2.10	1.70
SRU5018-4R7Y	4.7	± 30	8.5	7.96	80	36.0	2.00	1.55
SRU5018-6R8Y	6.8	± 30	7.5	7.96	60	50.0	1.45	1.20
SRU5018-100Y	10.0	± 30	12	2.52	50	65.0	1.25	1.05
SRU5018-150Y	15.0	± 30	12	2.52	40	100.0	0.95	0.80
SRU5018-220Y	22.0	± 30	12	2.52	28	160.0	0.68	0.65
SRU5018-330Y	33.0	± 30	13	2.52	23	220.0	0.66	0.56
SRU5018-470Y	47.0	± 30	13	2.52	18	330.0	0.54	0.45
SRU5018-680Y	68.0	± 30	12	2.52	16	480.0	0.37	0.36
SRU5018-101Y	100.0	± 30	15	0.796	15	620.0	0.32	0.31

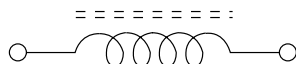
## General Specifications

Test Voltage.....0.1 V  
 Reflow Soldering ...230 °C, 50 sec. max.  
 Operating Temperature ..-40 °C to +125 °C  
 (Temperature rise included)  
 Storage Temperature...-40 °C to +125 °C  
 Resistance to Soldering Heat  
 .....260 °C for 10 sec.

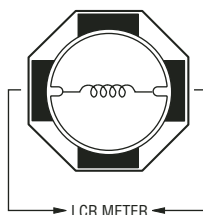
## Materials

Core.....Ferrite DR and RI core  
 Wire .....Enameled copper  
 Base .....LCP E4008  
 Terminal .....Ag/Ni/Sn  
 Rated Current  
 .....Ind. drop 35 % typ. at Isat  
 Temperature Rise  
 .....30 °C max. at rated Irms  
 Packaging.....1000 pcs. per reel

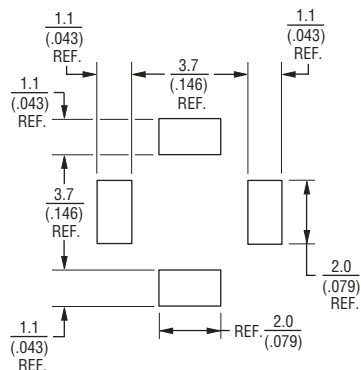
## Electrical Schematic



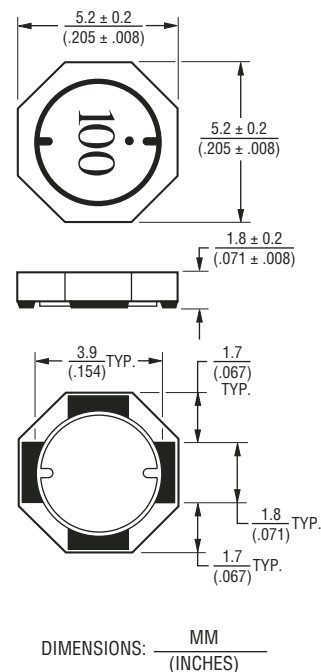
## Inductor Connection



## Recommended Layout



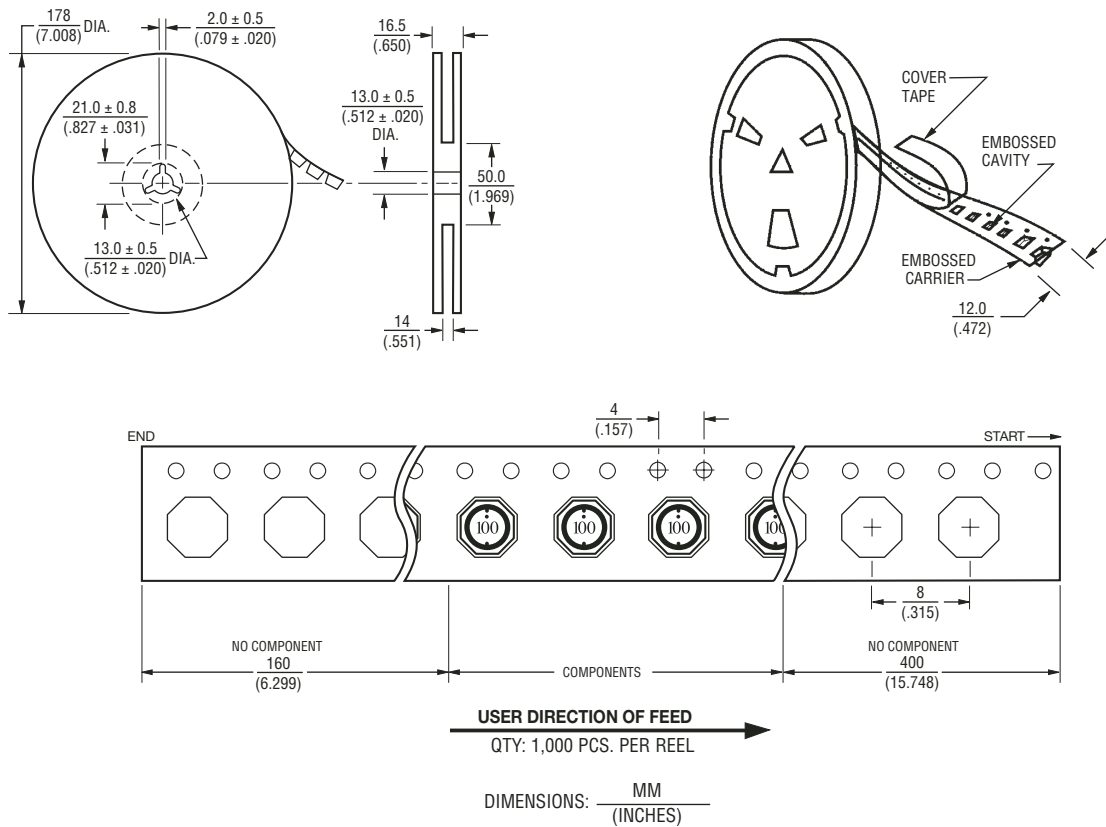
## Product Dimensions



# SRU5018 Series - Shielded SMD Power Inductors

**BOURNS®**

## Packaging Specifications



REV. 05/05

Specifications are subject to change without notice.  
Customers should verify actual device performance in their specific applications.